

INFORMATION NOTE



N° 069/15

Technology Update HybridPACK™ 1

Subject of Change: Introduction of refined system soldering process with Infineon's .XT-solder, solder stop line and refined DCB backside layout.

Products affected:	Type	SP N°	OPN	Package
	FS200R07A1E3	SP000663442	FS200R07A1E3BOSA1	AG-HYBRID1-1-1
	FS200T12A1T4	SP000840730	FS200T12A1T4BOSA1	AG-HYBRID1-1-1
	FS215R04A1E3D	SP001002716	FS215R04A1E3DBOMA1	AG-HYBRID1-1-1
	FS400R07A1E3	SP000663446	FS400R07A1E3BOSA1	AG-HYBRID1-1-1
	FS400R07A1E3_H5	SP000864748	FS400R07A1E3H5BPSA1	AG-HYBRID1-2-1
	HIG-FEB1	SP000663450	HIGFEB1BOSA1	AG-HYBRID1-1-1
	HIG-FEB1-1	SP001114634	HIGFEB11BOMA1	AG-HYBRID1-1-1
	HIG-FED1	SP000713564	HIGFED1BOSA1	AG-HYBRID1-1-1
	HIG-GD1	SP001034956	HIGGD1BOMA1	AG-HYBRID1-1-1

Reason of Change: Update of HybridPACK 1 with latest technologies for manufacturing harmonization.

Description of Change:	Old	New
■ Change of system solder process:	System solder process with standard solder and DCB layout	System solder process with Infineon's .XT solder, solder stop line and refined DCB backside layout

Assessment: No impact on electrical or thermal performance. Quality and reliability verified by qualification.
No change in form, fit and function.

Time Schedule: December 2015

Documentation: n.a.

If you have any questions, please do not hesitate to contact your local Sales office.

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